

## Specification for Approval

- DEVICE NUMBER: BL-3014A10-16-R80

SAMPLES  
ATTACHED AREA

DATE \ PAGE	1	2	3	4	5	6	7	8	9	1.0	CONTENTS
2018/5/31	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0	Initial Released
2019.10.22	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	Package drawing update

### FOR CUSTOMER'S APPROVAL STAMP OR SIGNATURE

APPROVED	PURCHASE	MANUFACTURE	QUALITY	ENGINEERING

佰鴻工業股份有限公司  
BRIGHT LED ELECTRONICS CORP.  
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[www.brtled.com](http://www.brtled.com)

ISSUED	APPROVED	PREPARED
張孝嚴	謝皓翔	羅培娟

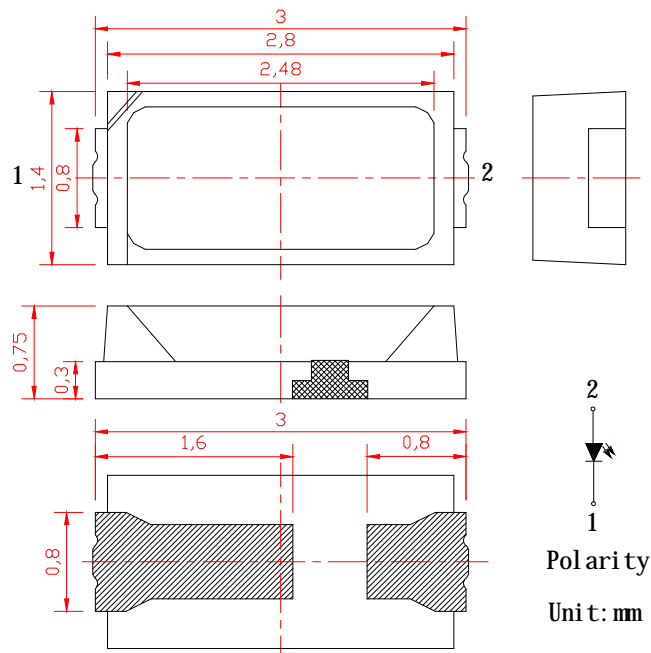
## ● Features:

1. Emitted Color: White..  
CCT: 4745~7040K
2. Lens Appearance: Yellow clear.
3. 3.0x1.4x0.75mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

## ● Applications:

1. Lighting
2. Automotive lighting.
3. Backlighting: LCDs
4. Status indicators: Consumer & industrial electronics.
5. General use.

## Package Dimensions:



## NOTES:

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.10$  mm unless otherwise specified.
3. Specifications are subject to change without notice.

## ● Absolute Maximum Ratings(Ta=25°C)

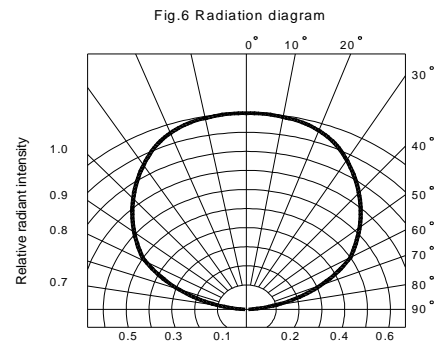
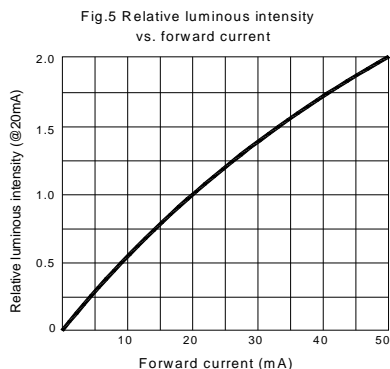
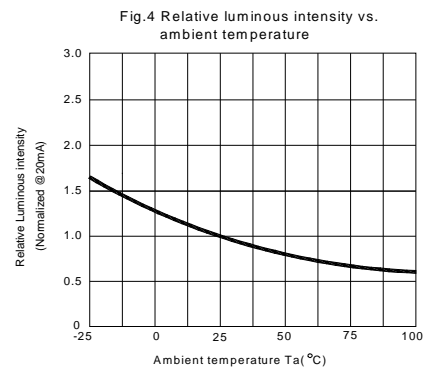
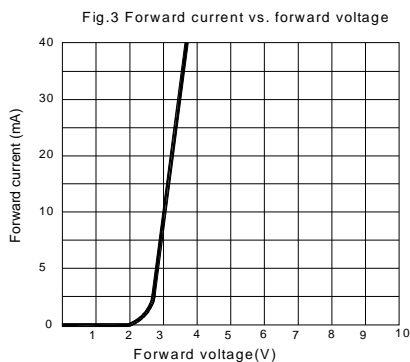
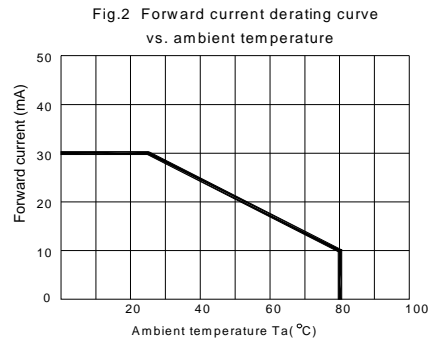
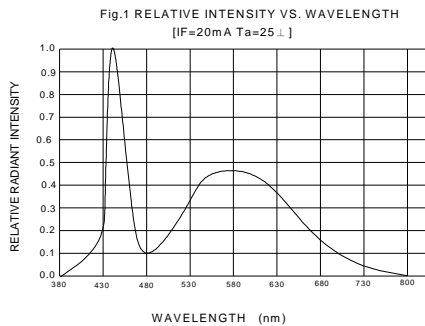
Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	100	mW
Forward Current	I <sub>F</sub>	30	mA
*1 Peak Forward Current	I <sub>FP</sub>	60	mA
LED Junction Temperature	T <sub>J</sub>	105	°C
Operating Temperature	Topr	-30~+80	°C
Storage Temperature	Tstg	-40~+100	°C
Soldering Temperature	Tsol	See Page 9	-

Note : I<sub>FP</sub> is pulse of 1/10 duty at 1KHz

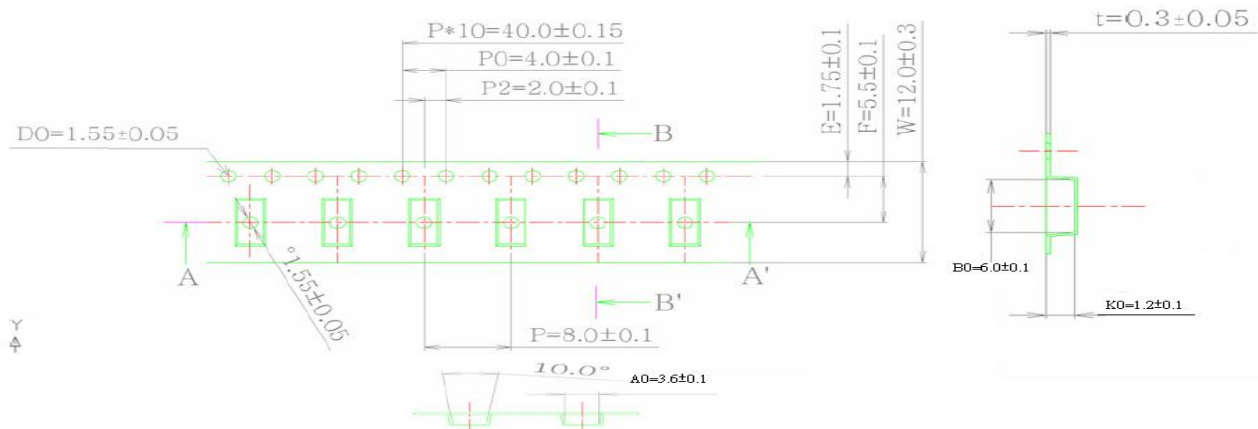
## Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
*2 Forward Voltage	V <sub>f</sub>	I <sub>F</sub> =20mA	2.8	-	3.4	V
*3 Luminous Intensity	I <sub>v</sub>		-	3000	-	mcd
Luminous Flux	Φ <sub>v</sub>		6	-	-	lm
*4 Chromaticity	x		-	0.33	-	-
Coordinates	y		-	0.33	-	
Color Temperature	CCT		4745	-	7040	K
Color Rendering Index	CRI		80	-	-	
Viewing Angle	2θ <sub>1/2</sub>		-	120	-	deg

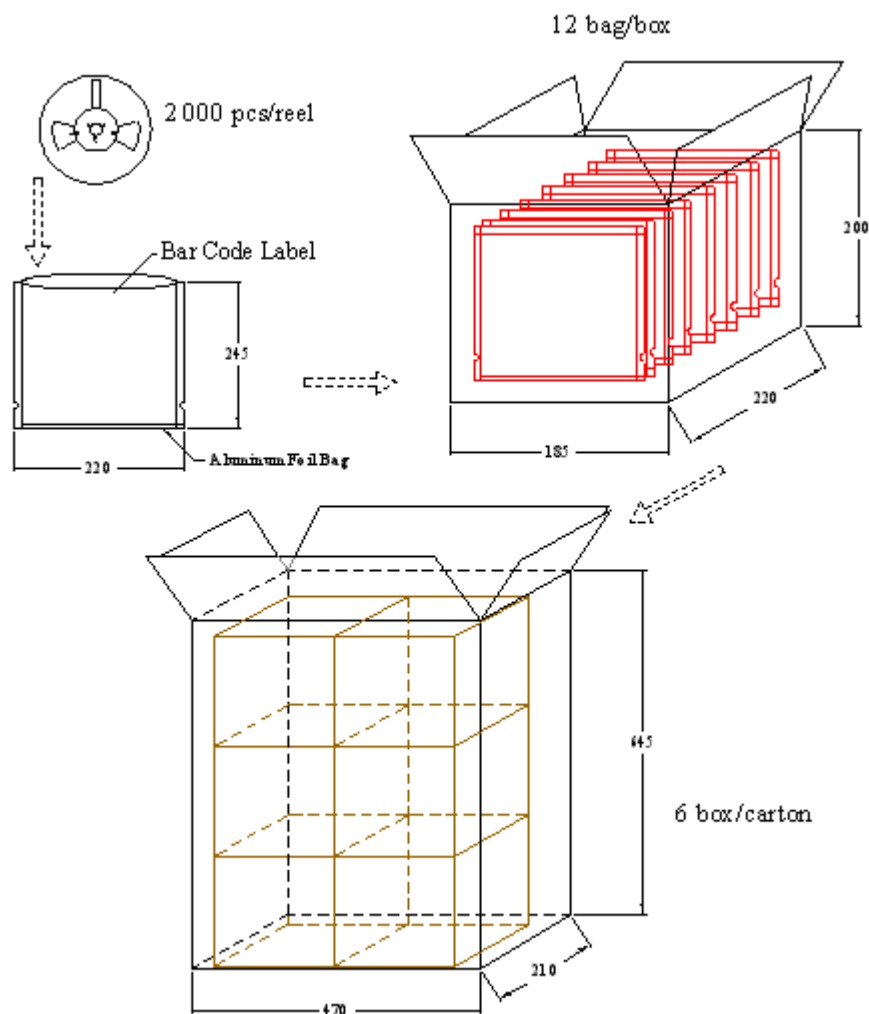
## Typical Electro-Optical Characteristics Curves.



## ● Tapping and packaging specifications(Units: mm)



## ● Package Method:(unit:mm)



## Intensity Bin Limits (At 20 mA)

<b>BIN CODE</b>	<b>Min. (mcd)</b>	<b>Max. (mcd)</b>
<b>ZX</b>	2250	2500
<b>ZY</b>	2500	2750
<b>ZZ</b>	2750	3000
<b>A0</b>	3000	3500
<b>A1</b>	3500	4000
<b>A2</b>	4000	4500

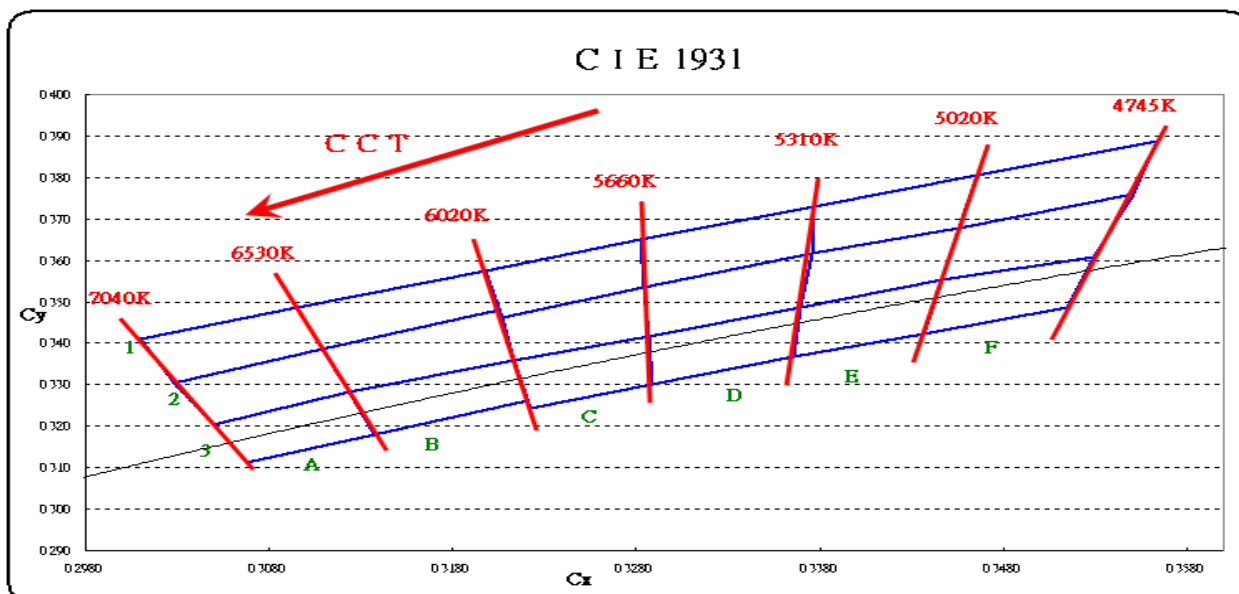
Tolerance for each Bin limit is  $\pm 10\%$ .

## Forward Voltage Bin Limits (At 20 mA)

<b>BIN CODE</b>	<b>Min.(v)</b>	<b>Max.(v)</b>
<b>Y</b>	2.8	2.9
<b>Z</b>	2.9	3.0
<b>A</b>	3.0	3.1
<b>B</b>	3.1	3.2
<b>C</b>	3.2	3.3
<b>D</b>	3.3	3.4

Tolerance for each Bin limit is  $\pm 0.02V$ .

## Color Temperature Bin Limits (At 20mA)

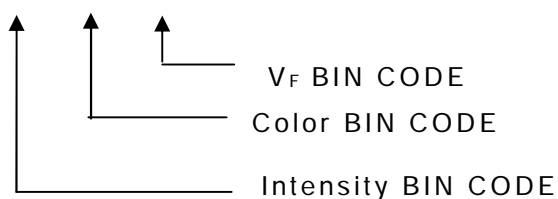


## Color Bin Limits (at 20mA)

BIN	CCT(K)		Chromaticity Coordinates					
A-1	6500K (6020-7040K)	6530-7040K	x	0.3109	0.3028	0.3010	0.3095	0.3109
A-2			y	0.3385	0.3304	0.3410	0.3485	0.3385
			x	0.3123	0.3050	0.3028	0.3109	0.3123
A-3			y	0.3283	0.3203	0.3304	0.3385	0.3283
			x	0.3137	0.3068	0.3050	0.3123	0.3137
B-1			y	0.3180	0.3113	0.3203	0.3283	0.3180
		6020-6530K	x	0.3205	0.3109	0.3095	0.3198	0.3205
y			0.3481	0.3385	0.3485	0.3575	0.3481	
B-2			x	0.3213	0.3123	0.3109	0.3205	0.3213
			y	0.3360	0.3282	0.3385	0.3481	0.3360
B-3			x	0.3221	0.3137	0.3123	0.3213	0.3221
			y	0.3261	0.3180	0.3282	0.3360	0.3261

BIN	CCT(K)		Chromaticity Coordinates					
C-1	5700K (5310-6020K)	5660-6020K	x	0.3284	0.3207	0.3198	0.3282	0.3284
C-2			y	0.3535	0.3462	0.3575	0.3650	0.3535
			x	0.3287	0.3213	0.3207	0.3284	0.3287
C-3			y	0.3417	0.3360	0.3462	0.3535	0.3417
			x	0.3289	0.3222	0.3213	0.3287	0.3289
D-1			y	0.3302	0.3243	0.3360	0.3417	0.3302
		5310-5660K	x	0.3376	0.3284	0.3282	0.3377	0.3376
y			0.3616	0.3535	0.3650	0.3730	0.3616	
D-2			x	0.3369	0.3287	0.3284	0.3376	0.3369
			y	0.3485	0.3417	0.3535	0.3616	0.3485
D-3			x	0.3366	0.3289	0.3287	0.3369	0.3366
			y	0.3369	0.3302	0.3417	0.3485	0.3369
E-1	5000K (4745-5310K)	5020-5310K	x	0.3456	0.3376	0.3377	0.3466	0.3456
E-2			y	0.3678	0.3616	0.3730	0.3806	0.3678
			x	0.3447	0.3369	0.3376	0.3456	0.3447
E-3			y	0.3553	0.3485	0.3616	0.3678	0.3553
			x	0.3437	0.3366	0.3369	0.3447	0.3437
F-1			y	0.3424	0.3369	0.3485	0.3553	0.3424
		4745-5020K	x	0.3551	0.3456	0.3466	0.3564	0.3551
y			0.3760	0.3678	0.3806	0.3888	0.3760	
F-2			x	0.3529	0.3447	0.3456	0.3551	0.3529
			y	0.3609	0.3553	0.3678	0.3760	0.3609
F-3			x	0.3515	0.3437	0.3447	0.3529	0.3515
			y	0.3487	0.3424	0.3553	0.3609	0.3487

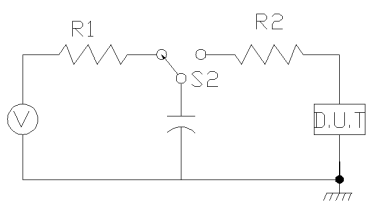
● BIN : x x x



## Notes:

1. Iv : Tolerance for each Bin limit is  $\pm 10\%$
2. Color : Tolerance for each Bin limit is  $\pm 0.005$
3. Bin categories are established for classification of products.  
Products may not be available in all bin categories

## ● Reliability Test

Test Item	Test Conditions	Test Hours/ Cycles	Result
Steady State Operating Life of High Temperature	$I_F=20\text{mA}$ $T_a=60^\circ\text{C}$	1,000hrs	0/20
Steady State Operating Life	$I_F=20\text{mA}$ $T_a=25^\circ\text{C}$	3,000hrs	0/20
Steady State Operating Life Low Temperature Condition1	$I_F=20\text{mA}$ $T_a=-30^\circ\text{C}$	1,000hrs	0/20
Steady State Operating Life Of High Humidity Heat	$I_F=20\text{mA}$ $T_a=60^\circ\text{C}$ RH=75%	1,000hrs	0/20
Thermal shock	$-45^\circ\text{C} \sim +125^\circ\text{C}$ 30 min 30 min	100cycle	0/20
Temperature & Humidity Cycling	$T_a=25^\circ\text{C} \sim +65^\circ\text{C} \sim -10^\circ\text{C}$ RH=90% RH, 24hr/1cycle	1cycle	0/20
Resistance to Soldering Heat	$T_{\text{sld}}=260^\circ\text{C}$ , 10sec (Pre treatment $30^\circ\text{C}$ , 70%, 168hrs)	2times	0/20
ESD(HBM)	 <p>-R1:10 K<math>\Omega</math>, R2:1.5 K<math>\Omega</math>, C:100 pF Discharge Time:3 times</p>	Min.2KV	0/5

## ● Judgment criteria of failure for the reliability

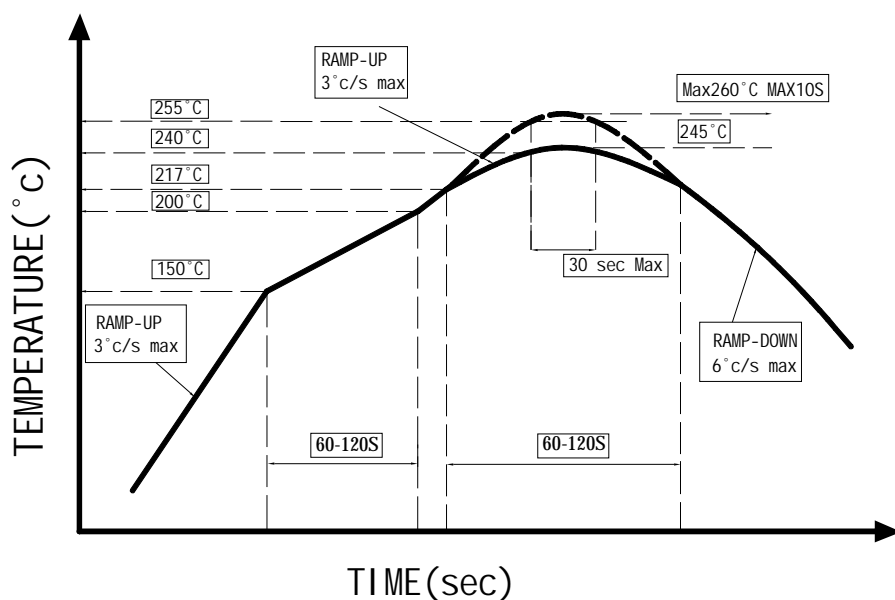
Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	$V_F$ (V)	$I_F=20\text{mA}$	Over $U^1 \times 1.2$
Reverse current	$I_R$ ( $\mu\text{A}$ )	$V_R=5\text{V}$	Over $U^1 \times 2$
Luminous intensity	$I_v$ (mcd)	$I_F=20\text{mA}$	Below $S^1 \times 0.5$

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.



## ● IR-Reflow Soldering



1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering .
2. Avoid rapid cooling or any excess vibration during temperature ramp-down process
3. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

## ● IRON Soldering

**300°C Within 3 sec, one time only.**

## ● Handling :

Care must be taken not to damage LED's epoxy resin while exposing to high temperature or contact LED's epoxy resin with hard or sharp objects, such as metal hook, tweezer or sand blasting.

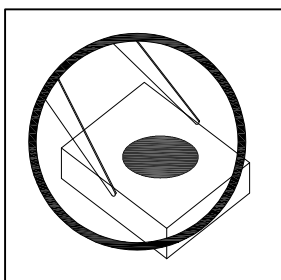
## ● Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic

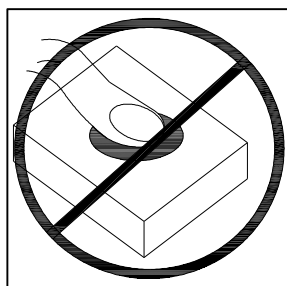
Significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated

LED products. Failure to comply might lead to damage and premature failure of the LED.

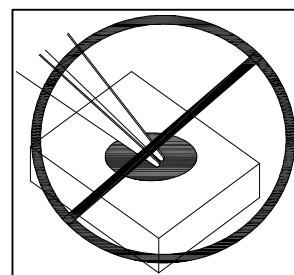
1. Handle the component along the side surfaces by using forceps or appropriate tools. (pic.1)
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry. (pic.2, pic.3)
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry. (pic.4)
4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. (pic.5)
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. (pic.5)
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production. (pic.5)



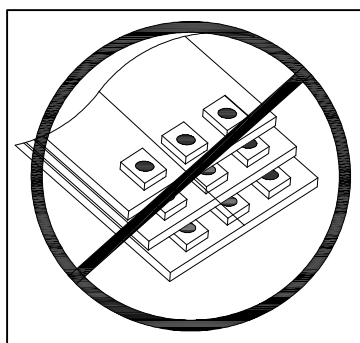
**Pic.1**



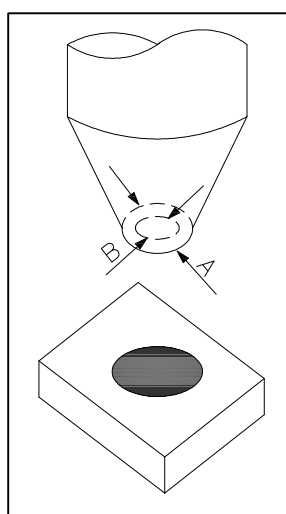
**Pic.2**



**Pic.3**



**Pic.4**



**Pic.5**

## ● Notes for designing:

Current limiting resistor must be used in the circuit to drive BRIGHT LEDs within the rated figures and not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF cycles. When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the BRIGHT LEDs.

## ● Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

Temperature : 5°C -30°C (41°F) Humidity : RH 60% Max.

After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:

Completed within 168 hours.

Stored at less than 30% RH.

Devices require baking before mounting, if:

(2) a or (2) b is not met.

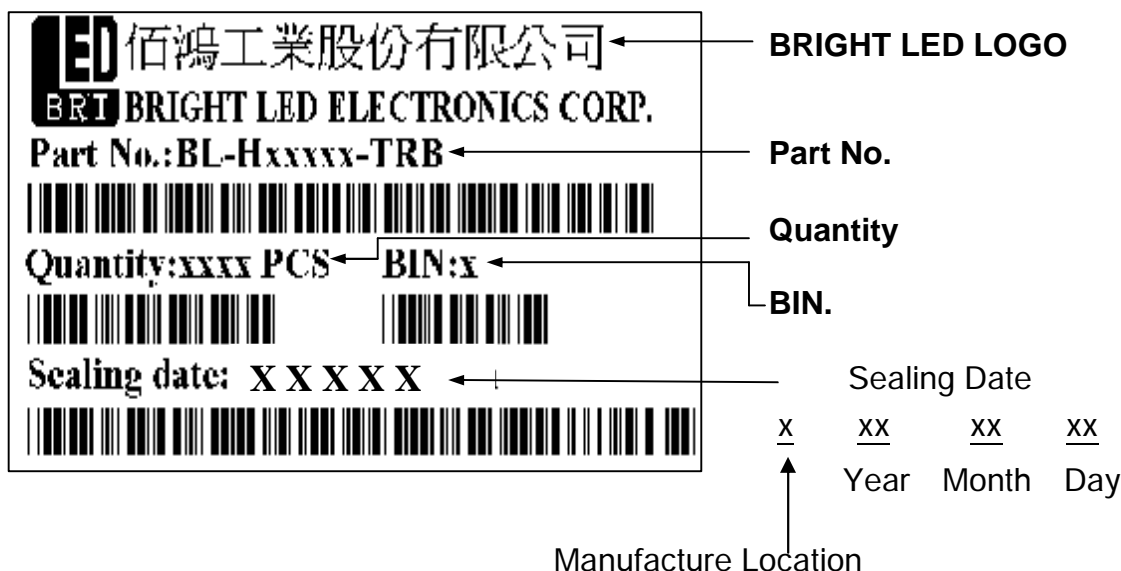
If baking is required, devices must be baked under below conditions:

48 hours at 60°C±3°C.

## ● Package and Label of Products:

Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached to each bag.

Label:



The diagram shows a rectangular label with the following fields and arrows:

- BRIGHT LED LOGO**: Points to the logo at the top left.
- Part No.**: Points to the text "Part No.: BL-Hxxxxx-TRB".
- Quantity**: Points to the text "Quantity:xxxx PCS".
- BIN.**: Points to the text "BIN:x".
- Sealing Date**: Points to the text "Sealing date: X X X X X".
- Manufacture Location**: Points to the text "X" below the sealing date.

The label also contains a barcode at the bottom and the company name in Chinese and English.